ITEQ
Your Partner of Advanced Materials & Mass Lam Service

IT-968SETC

High Tg / Lead Free / Ultra Low Loss Laminate & Prepreg

- 100G/400G Switch solution
- Lower Dk (3.16 @ 10GHz) and Ultra low Df (<0.0037 @ 10GHz)
- Stable Dk/Df with different environment
- Advanced High Tg Resin Technology

Laminate properties

Items	IPC TM-650	Typical Value	Unit
Peel Strength, minimum A. Low profile copper foil	2.4.8	2.5-3.5	lb/inch
Volume Resistivity	2.5.17.1	$1x10^{10}$	MΩ-cm
Surface Resistivity	2.5.17.1	$1x10^{10}$	MΩ
Moisture Absorption, maximum	2.6.2.1	0.1	%
Permittivity (Dk, 50% resin content) A. 1GHz B. 2GHz C. 5GHz D. 10GHz	2.5.5.13	 3.32 3.22 3.16 3.16	--
Loss Tangent (Df, 50% resin content) A. 1GHz B. 2GHz C. 5GHz D. 10GHz	2.5.5.13	 0.0029 0.0031 0.0033 0.0037	--
Flexural Strength, minimum A. Length direction B. Cross direction	2.4.4	 420-460 400-430	N/mm^2
Thermal Stress 10 s at 288°C A. Unetched B. Etched	2.4.13.1	 Pass Pass	Rating
Flammability	UL94	V-0	Rating
Glass Transition Temperature(TMA)	2.4.25	190	˚C
Decomposition Temperature	2.4.24.6	400	˚C
X/Y Axis CTE (40℃ to 125℃)	2.4.41	12/14	ppm/˚C
Z-Axis CTE A. Alpha 1 B. Alpha 2 C. 50 to 260 Degrees C	2.4.24	 45 260 2.2	 ppm/˚C ppm/˚C %
Thermal Resistance A. T260 B. T288	2.4.24.1	 >60 >60	 Minutes Minutes